

NLSV8T244

8-Bit Dual-Supply Non-Inverting Level Translator

The NLSV8T244 is a 8-bit configurable dual-supply voltage level translator. The input A_n and output B_n ports are designed to track two different power supply rails, V_{CCA} and V_{CCB} respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low-voltage translation from the input A_n to the output B_n port.

Features

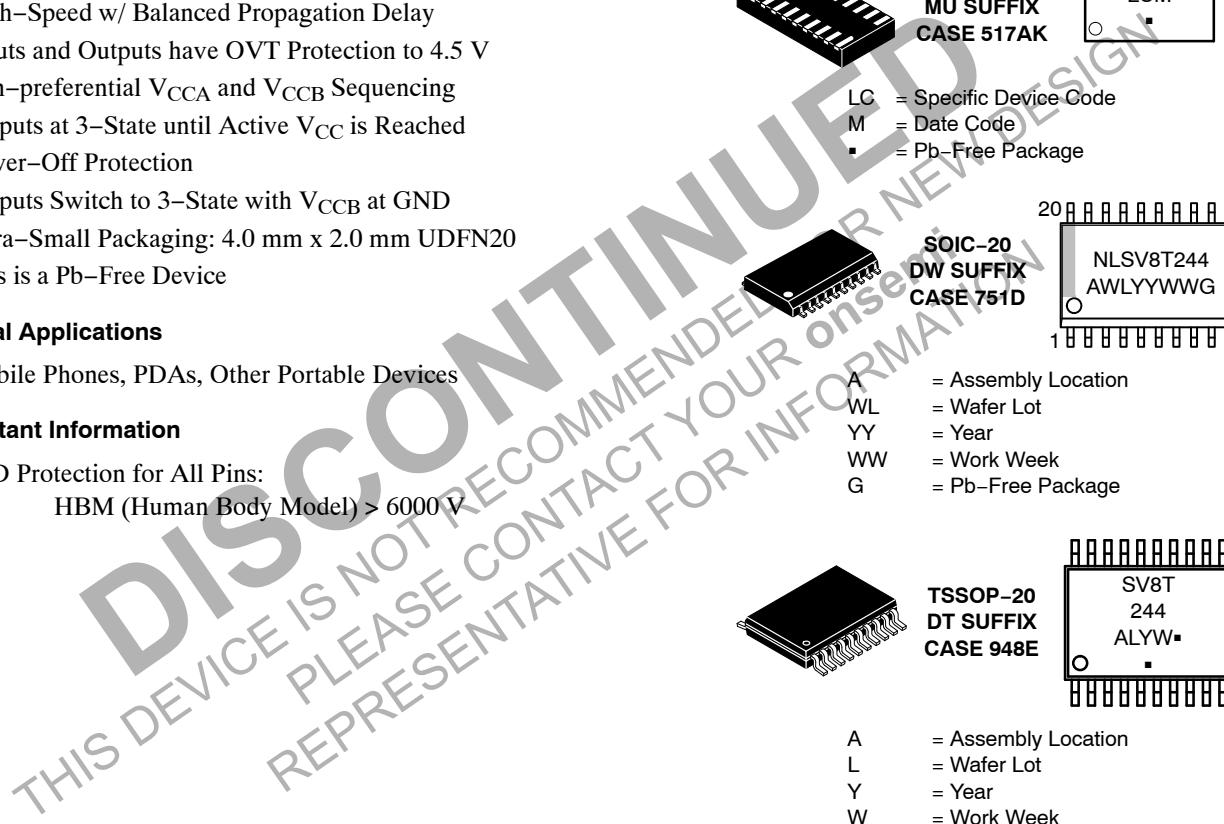
- Wide V_{CCA} and V_{CCB} Operating Range: 0.9 V to 4.5 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non-preferential V_{CCA} and V_{CCB} Sequencing
- Outputs at 3-State until Active V_{CC} is Reached
- Power-Off Protection
- Outputs Switch to 3-State with V_{CCB} at GND
- Ultra-Small Packaging: 4.0 mm x 2.0 mm UDFN20
- This is a Pb-Free Device

Typical Applications

- Mobile Phones, PDAs, Other Portable Devices

Important Information

- ESD Protection for All Pins:
HBM (Human Body Model) > 6000 V



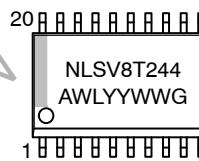
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MARKING DIAGRAMS



LC = Specific Device Code
M = Date Code
■ = Pb-Free Package



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

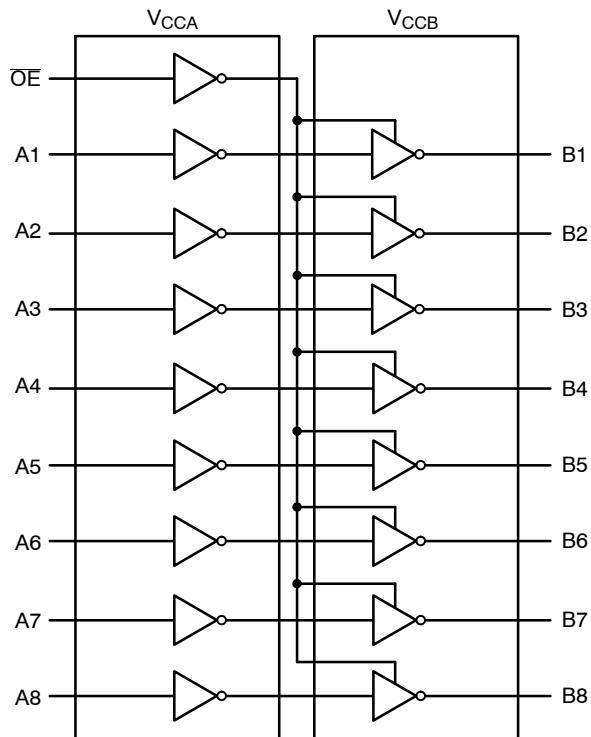


Figure 1. Logic Diagram

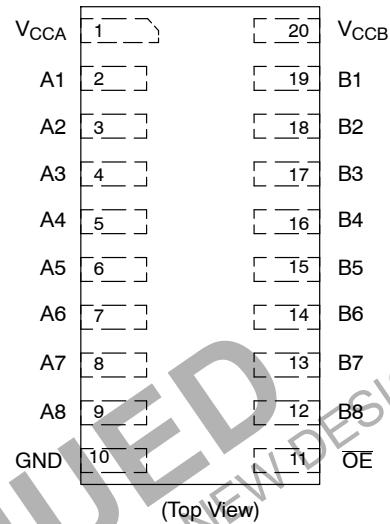


Figure 2. Pin Assignment

TRUTH TABLE

Inputs		Outputs
OE	A_n	B_n
L	L	L
L	H	H
H	X	3-State

PIN ASSIGNMENT

PIN	FUNCTION
VCCA	Input Port DC Power Supply
VCCB	Output Port DC Power Supply
GND	Ground
A_n	Input Port
B_n	Output Port
OE	Output Enable

MAXIMUM RATINGS

Symbol	Rating	Value	Condition	Unit
V_{CCA}, V_{CCB}	DC Supply Voltage	-0.5 to +5.5		V
V_I	DC Input Voltage	A_n	-0.5 to +5.5	V
V_C	Control Input	\bar{OE}	-0.5 to +5.5	V
V_O	DC Output Voltage (Power Down)	B_n	-0.5 to +5.5	$V_{CCA} = V_{CCB} = 0$
	(Active Mode)	B_n	-0.5 to +5.5	V
	(Tri-State Mode)	B_n	-0.5 to +5.5	V
I_{IK}	DC Input Diode Current	-20	$V_I < GND$	mA
I_{OK}	DC Output Diode Current	-50	$V_O < GND$	mA
I_O	DC Output Source/Sink Current	± 50		mA
I_{CCA}, I_{CCB}	DC Supply Current Per Supply Pin	± 100		mA
I_{GND}	DC Ground Current per Ground Pin	± 100		mA
T_{STG}	Storage Temperature	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CCA}, V_{CCB}	Positive DC Supply Voltage	0.9	4.5	V
V_I	Bus Input Voltage	GND	4.5	V
V_C	Control Input	\bar{OE}	GND	V
V_{IO}	Bus Output Voltage (Power Down Mode)	GND	4.5	V
	(Active Mode)	B_n	GND	V_{CCB}
	(Tri-State Mode)	B_n	GND	V
T_A	Operating Temperature Range	-40	+85	°C
$\Delta t / \Delta V$	Input Transition Rise or Rate V_I , from 30% to 70% of V_{CC} ; $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	nS

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CCA} (V)	V _{CCB} (V)	-40°C to +85°C		Unit
					Min	Max	
V _{IH}	Input HIGH Voltage (An, OE)		3.6 – 4.5	0.9 – 4.5	2.2	–	V
			2.7 – 3.6		2.0	–	
			2.3 – 2.7		1.6	–	
			1.4 – 2.3		0.65 * V _{CCA}	–	
			0.9 – 1.4		0.9 * V _{CCA}	–	
V _{IL}	Input LOW Voltage (An, OE)		3.6 – 4.5	0.9 – 4.5	–	0.8	V
			2.7 – 3.6		–	0.8	
			2.3 – 2.7		–	0.7	
			1.4 – 2.3		–	0.35 * V _{CCA}	
			0.9 – 1.4		–	0.1 * V _{CCA}	
V _{OH}	Output HIGH Voltage	I _{OH} = -100 µA; V _I = V _{IH}	0.9 – 4.5	0.9 – 4.5	V _{CCB} – 0.2	–	V
		I _{OH} = -0.5 mA; V _I = V _{IH}	0.9	0.9	0.75 * V _{CCB}	–	
		I _{OH} = -2 mA; V _I = V _{IH}	1.4	1.4	1.05	–	
		I _{OH} = -6 mA; V _I = V _{IH}	1.65	1.65	1.25	–	
			2.3	2.3	2.0	–	
		I _{OH} = -12 mA; V _I = V _{IH}	2.3	2.3	1.8	–	
			2.7	2.7	2.2	–	
		I _{OH} = -18 mA; V _I = V _{IH}	2.3	2.3	1.7	–	
			3.0	3.0	2.4	–	
		I _{OH} = -24 mA; V _I = V _{IH}	3.0	3.0	2.2	–	
V _{OL}	Output LOW Voltage	I _{OL} = 100 µA; V _I = V _{IL}	0.9 – 4.5	0.9 – 4.5	–	0.2	V
		I _{OL} = 0.5 mA; V _I = V _{IL}	1.1	1.1	–	0.3	
		I _{OL} = 2 mA; V _I = V _{IL}	1.4	1.4	–	0.35	
		I _{OL} = 6 mA; V _I = V _{IL}	1.65	1.65	–	0.3	
		I _{OL} = 12 mA; V _I = V _{IL}	2.3	2.3	–	0.4	
			2.7	2.7	–	0.4	
		I _{OL} = 18 mA; V _I = V _{IL}	2.3	2.3	–	0.6	
			3.0	3.0	–	0.45	
I _I	Input Leakage Current	V _I = V _{CCA} or GND	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	µA
			0	0.9 – 4.5	-1.0	1.0	
I _{OFF}	Power-Off Leakage Current	OE = 0 V	0.9 – 4.5	0	-1.0	1.0	µA
			0	0	-1.0	1.0	
I _{CCA}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	µA
I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	µA
I _{CCA} + I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	4.0	µA
ΔI _{CCA}	Increase in I _{CC} per Input Voltage, Other Inputs at V _{CCA} or GND	V _I = V _{CCA} – 0.6 V; V _I = V _{CCA} or GND	4.5 3.6	4.5 3.6	–	10 5.0	µA
ΔI _{CCB}	Increase in I _{CC} per Input Voltage, Other Inputs at V _{CCA} or GND	V _I = V _{CCA} – 0.6 V; V _I = V _{CCA} or GND	4.5 3.6	4.5 3.6	–	10 5.0	µA
I _{OZ}	I/O Tri-State Output Leakage Current	T _A = 25°C, OE = 0 V	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	µA

TOTAL STATIC POWER CONSUMPTION ($I_{CCA} + I_{CCB}$)

V_{CCA} (V)	-40°C to +85°C										Unit	
	V_{CCB} (V)											
	4.5		3.3		2.8		1.8		0.9			
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
4.5		2		2		2		2		< 1.5	μA	
3.3		2		2		2		2		< 1.5	μA	
2.8		< 2		< 1		< 1		< 0.5		< 0.5	μA	
1.8		< 1		< 1		< 0.5		< 0.5		< 0.5	μA	
0.9		< 0.5		< 0.5		< 0.5		< 0.5		< 0.5	μA	

NOTE: Connect ground before applying supply voltage V_{CCA} or V_{CCB} . This device is designed with the feature that the power-up sequence of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CCA} (V)	-40°C to +85°C										Unit	
			V_{CCB} (V)											
			4.5		3.3		2.8		1.8		1.2			
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
t_{PLH} , t_{PHL} (Note 1)	Propagation Delay, A_n to B_n	4.5		1.6		1.8		2.0		2.1		2.3	nS	
		3.3		1.7		1.9		2.1		2.3		2.6		
		2.8		1.9		2.1		2.3		2.5		2.8		
		1.8		2.1		2.4		2.5		2.7		3.0		
		1.2		2.4		2.7		2.8		3.0		3.3		
t_{PZH} , t_{PZL} (Note 1)	Output Enable, OE to B_n	4.5		2.6		3.8		4.0		4.1		4.3	nS	
		3.3		3.7		3.9		4.1		4.3		4.6		
		2.5		3.9		4.1		4.3		4.5		4.8		
		1.8		4.1		4.4		4.5		4.7		5.0		
		1.2		4.4		4.7		4.8		5.0		5.3		
t_{PHZ} , t_{PLZ} (Note 1)	Output Disable, OE to B_n	4.5		2.6		3.8		4.0		4.1		4.3	nS	
		3.3		3.7		3.9		4.1		4.3		4.6		
		2.5		3.9		4.1		4.3		4.5		4.8		
		1.8		4.1		4.4		4.5		4.7		5.0		
		1.2		4.4		4.7		4.8		5.0		5.3		
t_{OSHL} , t_{OSLH} (Note 1)	Output to Output Skew, Time	4.5		0.15		0.15		0.15		0.15		0.15	nS	
		3.3		0.15		0.15		0.15		0.15		0.15		
		2.5		0.15		0.15		0.15		0.15		0.15		
		1.8		0.15		0.15		0.15		0.15		0.15		
		1.2		0.15		0.15		0.15		0.15		0.15		

1. Propagation delays defined per Figure 3.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
C_{IN}	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or $V_{CCA/B}$	3.5	pF
$C_{I/O}$	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or $V_{CCA/B}$	5.0	pF
C_{PD}	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or V_{CCA} , $f = 10$ MHz	20	pF

2. Typical values are at $T_A = +25^\circ\text{C}$.

3. C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from:
 $I_{CC(\text{operating})} \cong C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$ where $I_{CC} = I_{CCA} + I_{CCB}$ and N_{SW} = total number of outputs switching.

NLSV8T244

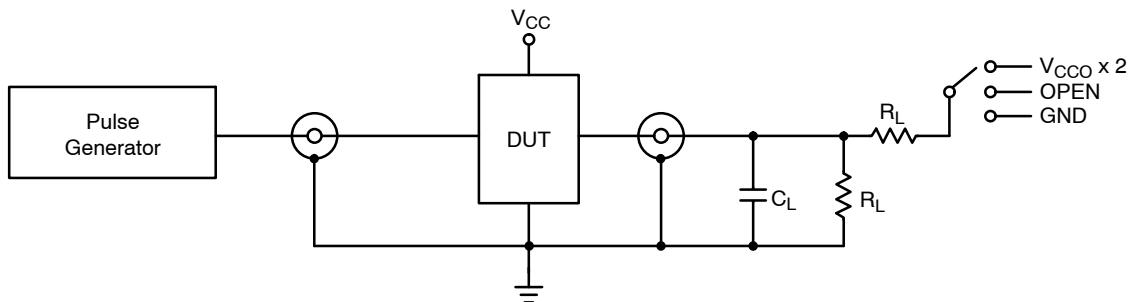
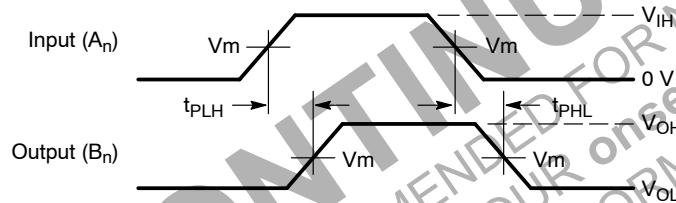


Figure 3. AC (Propagation Delay) Test Circuit

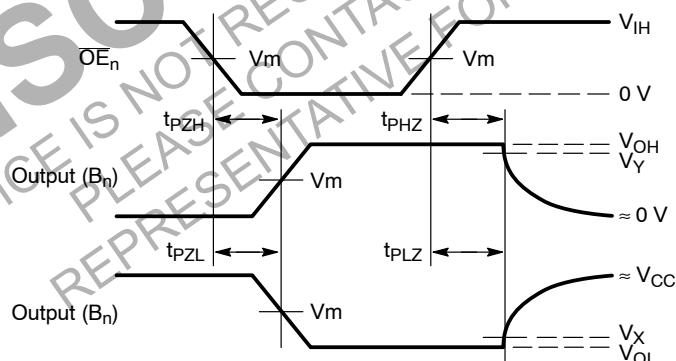
Test	Switch
t_{PLH}, t_{PHL}	OPEN
t_{PLZ}, t_{PZL}	$V_{CCO} \times 2$
t_{PHZ}, t_{PZH}	GND

$C_L = 15 \text{ pF}$ or equivalent (includes probe and jig capacitance)
 $R_L = 2 \text{ k}\Omega$ or equivalent
 Z_{OUT} of pulse generator = 50Ω



Waveform 1 – Propagation Delays

$t_R = t_F = 2.0 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$



Waveform 2 – Output Enable and Disable Times

$t_R = t_F = 2.0 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$

Figure 4. AC (Propagation Delay) Test Circuit Waveforms

Symbol	V_{CC}				
	3.0 V – 4.5 V	2.3 V – 2.7 V	1.65 V – 1.95 V	1.4 V – 1.6 V	0.9 V – 1.3 V
V_{mA}	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$
V_{mB}	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$
V_X	$V_{OL} \times 0.1$				
V_Y	$V_{OH} \times 0.9$				

NLSV8T244

ORDERING INFORMATION

Device	Package	Shipping [†]
NLSV8T244MUTAG	UQFN20 (Pb-Free)	3000 / Tape & Reel
NLSV8T244DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel
NLSV8T244DWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

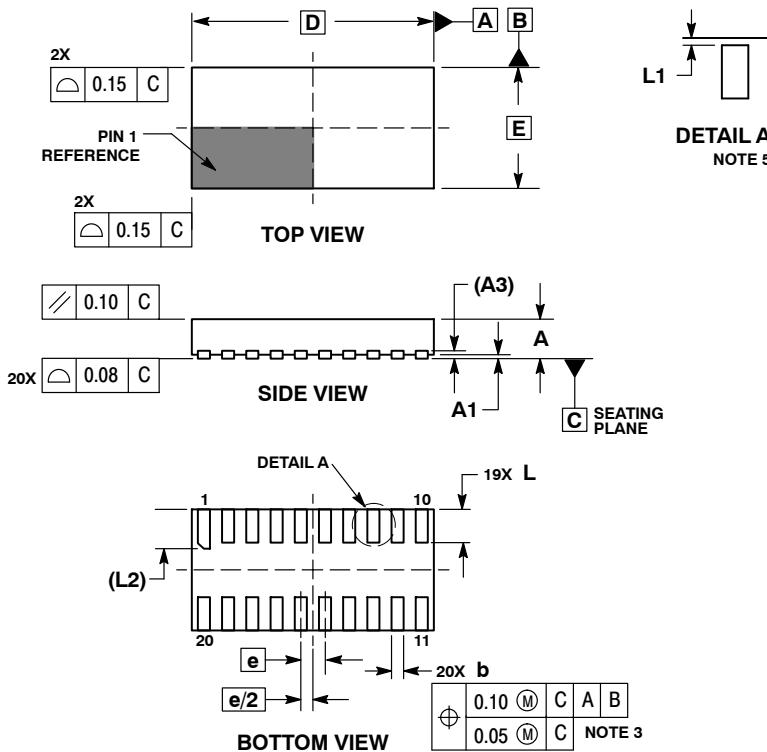
DISCONTINUED
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN
PLEASE CONTACT YOUR **onsemi**
REPRESENTATIVE FOR INFORMATION



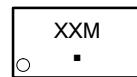
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UDFN20 4x2, 0.4P
CASE 517AK
ISSUE O

DATE 14 NOV 2006

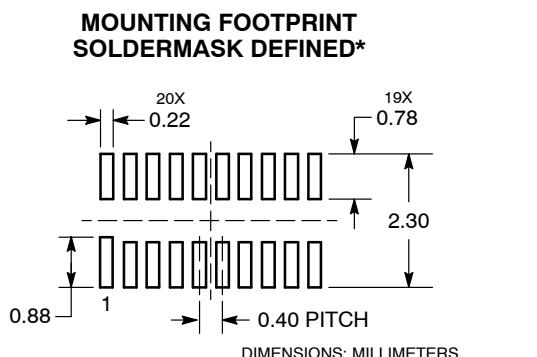


MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	4.00	BSC
E	2.00	BSC
e	0.40	BSC
L	0.50	0.60
L1	0.00	0.03
L2	0.60	0.70

GENERIC
MARKING DIAGRAM*

XX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



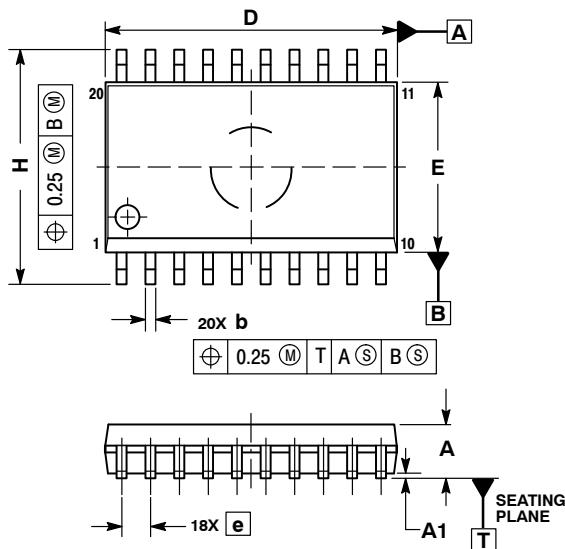
*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN20 4x2, 0.4P	PAGE 1 OF 1

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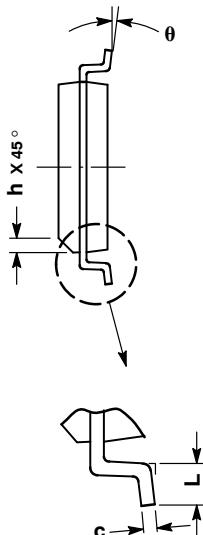


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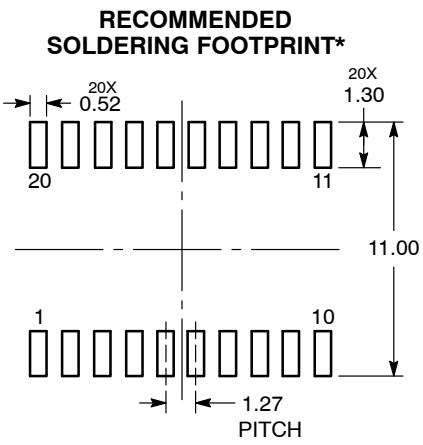
SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015



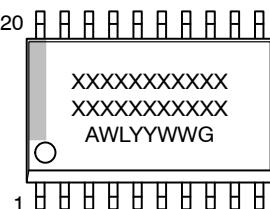
NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

MILLIMETERS		
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °



*For additional information on our Pb-Free strategy and soldering details, please download the [onsemi](#) Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

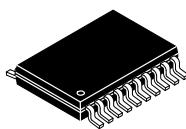


XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

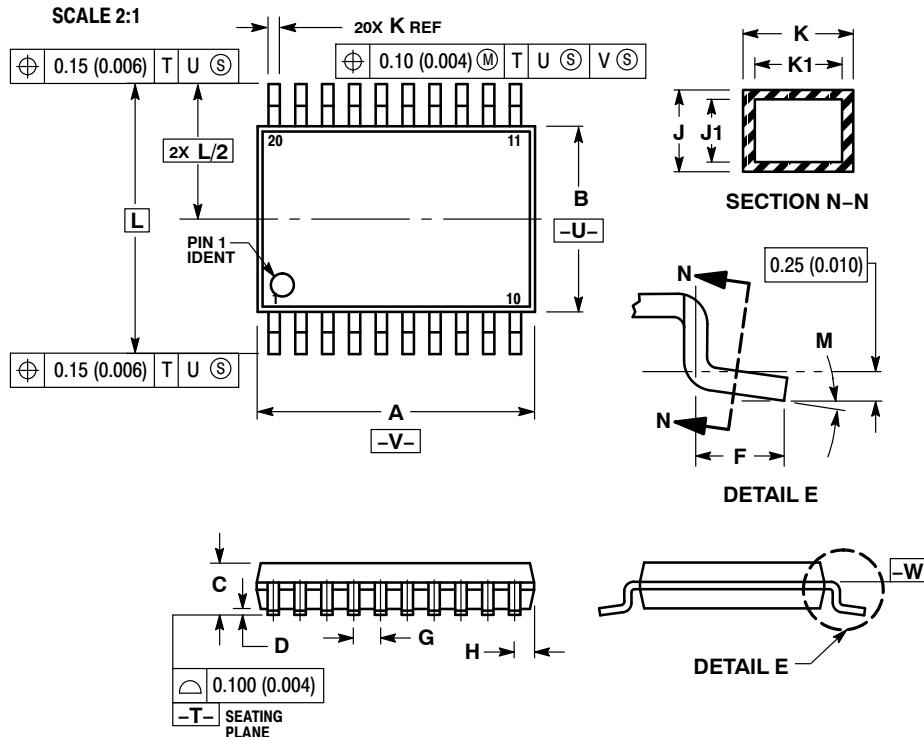
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOIC-20 WB	PAGE 1 OF 1

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TSSOP-20 WB
CASE 948E
ISSUE D

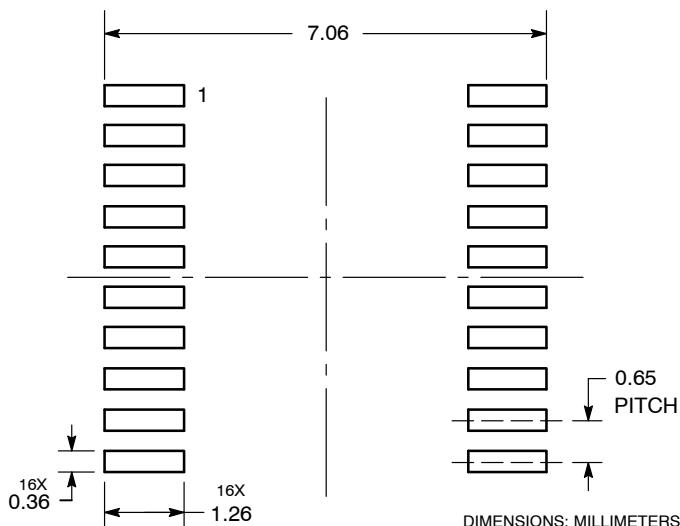
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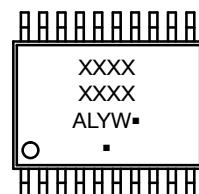
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED
SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TSSOP-20 WB	PAGE 1 OF 1

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